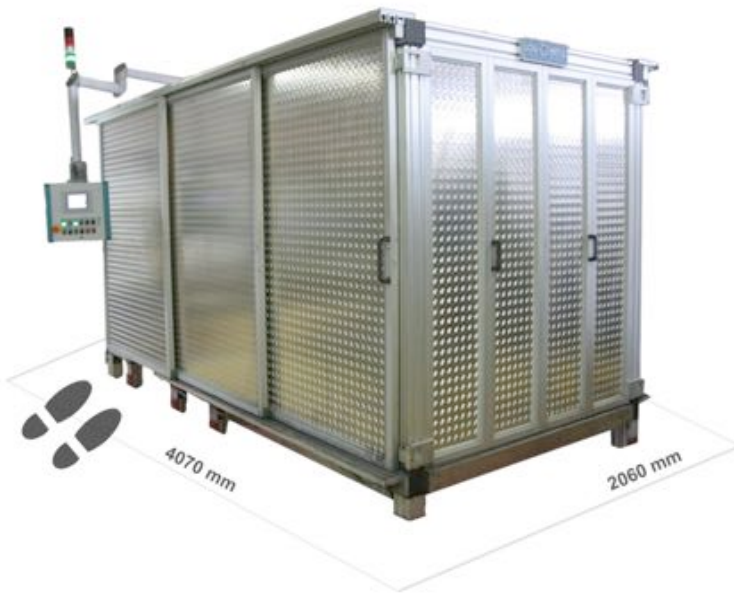


# Diamond Wire Cropper LDTC Series



## Features

Special development for multi-crystalline silicon brick top & tail cutting

- High output with low costs
- Cutting with diamond multi wire concept
- 20, 25 or 36 (G6) bricks in one run
- Water based coolant instead of slurry
- Easy handling: QUICK, SIMPLE ingot loading and unloading
- Ingot clamping with vacuum table
- Automatic cutting process

## Capacity

TYPE	Bricks / day
LDTC 20	60
LDTC 25	75
LDTC 36	108

## Technical data

Brick dimension	156 mm x 156 mm
Brick length	~ 300 mm
Brick weight	~ 20 kg / pc
Wire diameter	350 – 450 µm
Wire speed	5 – 14.2 m / sec
In-feed	5 – 50 µm / sec
Brick clamping	with vacuum table
Coolant	water (or LD1)
Water tank capacity	1,500 l (closed loop)
El. connection	400 V, 50 Hz 36 kVA
Software	Siemens touch panel
Layout	4,000x2,500x2,700 mm
Weight	~ 5,500 kg

